




## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<b>* : Required Field</b>			

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2017-05-12</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>MDG MD CHAMPION</b>	<b>Representative Title</b>	<b>MDG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8L152M8T7	U61S*768XXXZ	A	959	2017-05-12
	Amount	UoM	Unit type	ST ECOPACK Grade
	645.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NiPdAu	NAC	Copper		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	80	L Bend	
Comment	Package : 1S LQFP 80 14x14x1.4 1 0062342			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	U615*768XXXZ				7000000.0	1000000.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.688	mg	supplier	die	Silicon (Si)	7440-21-3		6.482	mg	969199	10050
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2691	28
				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	8971	93
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.007	mg	1047	11
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1346	14
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	2392	25
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	14354	149
Lead-frame	M-011 Other inorganic materials	130.716	mg	supplier	alloy	Copper (Cu)	7440-50-8		125.749	mg	962000	194960
				supplier	alloy	Nickel (Ni)	7440-02-0		3.921	mg	30000	6080
				supplier	alloy	Silicium (Si)	7440-21-3		0.850	mg	6500	1317
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.196	mg	1500	304
Lead-frame Coating	M-011 Other inorganic materials	0.925	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.848	mg	916800	1315
				supplier	coating	Palladium (Pd)	7440-05-3		0.054	mg	58700	84
				supplier	coating	Gold (Au)	7440-57-5		0.023	mg	24500	35
Die Attach	M-011 Other inorganic materials	3.617	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.848	mg	787500	4416
				supplier	glue or soft solder	Urethane acrylate oligomer	Proprietary		0.253	mg	70000	392
				supplier	glue or soft solder	Méthacrylate	Proprietary		0.253	mg	70000	392
				supplier	glue or soft solder	Acrylate	Proprietary		0.253	mg	70000	392
Wires	M-011 Other inorganic materials	2.018	mg	supplier	glue or soft solder	NMP	872-50-4		0.009	mg	2500	14
				supplier	Bonding wire	Gold (Au)	7440-57-5		2.018	mg	1000000	3129
Encapsulation	M-011 Other inorganic materials	501.028	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		34.333	mg	68525	53229
				supplier	Moulding Compound	Phenol Resin	Proprietary		24.524	mg	48947	38021
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		434.814	mg	867844	674130
				supplier	Moulding Compound	Carbon-black	1333-86-4		2.452	mg	4895	3802
				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		4.905	mg	9789	7604
Finishing	M-011 Other inorganic materials	0.009	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.008	mg	916800	13
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.001	mg	58700	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0